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Applicant: WILLIAM J. GREEN

Examiner: Unassigned

Serial No. 09/002,031

Group Art Unit: Unassigned

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For: MOLDED ELECTRONIC PACKAGE AND
METHOD OF PREPARATION

PETITION FOR FILING FOREIGN LICENSE
UNDER 37 C.F.R. 5.14(a)

~~09/002,031~~
The Honorable Commissioner of
Patents and Trademarks
Washington, D.C. 20231

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A complete copy of the application as filed is attached hereto along with the appropriate Petition Fee of \$130.00 as required by 37 C.F.R. 1.17(h).

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Also attached to this Petition is a POWER TO INSPECT granting the undersigned the authority to inspect the application and facilitate its examination. This Petition is also accompanied by

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Respectfully submitted,

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Title: **MOLDED ELECTRONIC PACKAGE AND METHOD OF
PREPARATION**

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[Title 35, United States Code (1952) Sections 184, 185, 186]

I hereby certify that this New Application transmittal documents referred to as attached thereto are being with the United States Postal Service on this date in an envelope as "Express Mail Post Office to Address Mailing Label Number EM4135749640 to the Assistant Commissioner for Patents, Washington

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PATENT

INVENTOR: GREEN, WILLIAM J.
U.S. citizen

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MOLDED ELECTRONIC PACKAGE AND METHOD OF PREPARATION

This invention relates to the construction of a packaged electronic circuit comprising of a molded plastic support base having the capacity to accept and hold electronic devices or subassemblies in a pocket within the molded substrate, and 15 positioning them for interconnection (hereinafter referred to as "Molded Electronic Package"). The connection to the electronic devices or subassemblies is intricately formed with the placement of the circuit traces on the substrate. This is usually done at the surface level. The formation of the circuit traces by Polymer 20 Thick Film and the attachment to electronic devices is achieved by Polymer Thick-Film technology while the substrate is formed with plastic molding technology. The electronic devices may be semiconductors or other active components, or passive components such as Thick Film resistors or capacitors. While molded substrates are not new, and the use of Polymer Thick-Film technology and Thick Film Technology are not new, the combination 25 of the molded substrate with a pocket built in the molded substrate and interconnecting with Polymer Thick Film technology is new and fulfills a long felt need to be able to ^{reduce} save the surface area above the trace area for other circuits traces and electronic devices. 30 Others have tried to accomplish this by other means of interconnecting by layering circuit boards as discussed below, but

only with the advent of the new Polymer Thick Films and the new molded plastic resins which have only recently become available can we now accomplish the connecting of the electronic device in the pocket of the substrate material. The pocket permits the 5 electronic device to be supported by the substrate instead of being supported on the trace which allows for the use of the new Polymer Thick Film technology which previously did not exist. This long felt need to further reduce the size of circuit boards for ever smaller products while containing or reducing costs of the 10 resulting circuits has until now been unanswered by conventional methods.

BACKGROUND OF THE INVENTION

15 A traditional printed circuit board comprises a supporting substrate and copper-foil circuit traces. These traces are usually formed by the chemical etching of a pattern defined onto a laminated copper surface. Sometimes both front and back sides of the substrate carry circuit traces. Two-sided, or double-sided 20 designs usually are interconnected through vias (holes) that have copper deposited around the hole walls. A related technology exists known as Thick Film. Here the supporting substrate comprises flat, thin pieces of alumina (Al_2O_3) on which the traces are printed with an ink containing metal, glass frit, and other 25 additives. When fired at the correct temperatures the ink fuses

semi-conductor corporation.
3 resistors and other

to form conductive traces to which components can be soldered. An important feature to Thick-Film technology is that conductive traces can be interconnected by printed inks ^{which now} having specific electrical resistivity ^{by} after being heated in a kiln (firing).

5 ^{which} A lesser known technology exists known as Polymer Thick Film,
[Here] conductive traces can be prepared on printed circuit board substrate using polymer inks that contain polymer resins and metals, usually silver. Typically heat is used to "cure" or "set" the polymers in the inks to form reasonably stable circuit traces. In
10 a manner similar to the Thick-Film process, carbon-filled inks can be used to interconnect circuit traces with specific electrical resistances. Carbon prints, known as Polymer Thick Film resistors, can be printed onto traditional copper foil traces, or onto printed Polymer Thick Film conductive circuit traces.

15 Countless variations of printed circuit boards exist, and many variations of the Polymer Thick Film process also exist. One application of both the printed circuit board process and the Polymer Thick Film process is the Molded Circuit board. Here the process of converting a laminated sheet of material into the proper
20 circuit board dimensions and having all the necessary holes, slots, and shapes are replaced by molding these features into the board. Circuit traces are applied to a board either during or after the ^{process} molding process. One method for adding the traces was to print them with conductive Polymer Thick Film inks.

25 In the past the molded board with Polymer Thick Film traces

(baking of the Polymer Thick Film ink creates the conductive circuit traces) found limited acceptance for a number of reasons. Printed Polymer Thick Film conductive traces have [more] resistance than copper foil traces. Also, electronic devices cannot be 5 soldered to most Polymer Thick Film traces. Those electronic devices that were attached to solderable Polymer Thick Film inks did not have good adhesion to the molded substrate after the soldering process. Some Polymer Thick Film conductive inks contain lead which causes environmental concerns and which limits the 10 ability to recycle the materials. Additionally, the molded plastic that could withstand soldering temperatures without warping were the engineering grade materials which are higher quality performing materials. These are more expensive, however, and when used, the cost advantage of the molding process is often lost. Some simple 15 applications of the Molded Board with Polymer Thick Film traces (but without pockets) designed to fit into a connector have been used commercially, but in general commercial production of this type product has been limited.

Lassen's United States patent No. 4,602,318 describes 20 achieving high density electronic networks by depositing filaments onto a substrate and encapsulating the filaments to achieve dimensional stability. Filaments are conductive or made conductive by various means. Access to these conductive traces is produced with the use of a high energy beam to cut through and expose the 4

filaments. Lassen claims the use of epoxy resin sheets, and polyimide resin sheets to create his circuitry.

Parker's United States patent No. 4,912,844 describes using a heated punch to define grooves and holes in a substrate. The 5 grooves are then filled with solder to create a circuit trace which connects electronic devices.

Beaman's United States patent No. 5,371,654 describes a three dimensional electronic package with a plurality of assemblies interconnected by aligning the assemblies so they are adjacent, and 10 interconnected by some means such as an elastomeric material, but other than a Polymer Thick Film.

Capote's United States patent No. 5,376,403 describes ink formulations which can be used to form circuit traces, but Capote does not describe or claim uses for [his ink.] *from*

15 Miller's United States patent No. 5,420,755 places a component *in* ^{part of} a hole cut into standard circuit board material, but does not claim using molded pockets in circuit boards. The component is attached with a standard solder connection. Placement of the component is in a cut hole and the solder joint is not different 20 from using any common commercial solder joint to connect the electronic devices.

McGinley's United States patents No. 5,599,595 and No. 5,688,146 describes how circuit traces can be added to molded plastic to achieve a printed connector assembly. McGinley uses

current technology to attach printed Polymer Thick Film conductive traces to the top surface of the Polymer Thick Film traces. McGinley uses current technology Polymer Thick Film methods to print resistors on the circuitry of the connector.

5 Marrocco's United States patents No. 5,646,231, No. 5,646,232, and No. 5,654,392 describe the use of rigid-rod polymers to form a plastic molded circuit board. No mention is made as to how this is done, nor are any claims made concerning molded pockets in the substrate or attachments of the electrical devices placed in the
10 pockets.

SUMMARY OF THE INVENTION

The present invention provides a cost-effective, highly functional packaged electronic circuit by combining the advantages 15 of molded substrates, Thick Film construction, and Polymer Thick Film technology in a single package. To do this I designed the molded support to accept inserted electronic devices and/or subcircuits and connecting them with additive circuitry which both adheres to the substrate and connects the individual components.
20 In Fig. 1 one ^{complementary} variation of this concept is shown. The attached electronic devices can be a resistor, capacitor, LED, or it can be an electromechanical device such as a connector pin or an off/on switch, or a bioelectrical functional component. Simple functional features can also be incorporated into the molded design such as

heat sinks, pins that connect front side circuitry to back side circuitry, or thermal vias (holes or openings in the board). The electronic device in the pocket can attach on a planar level of the substrate (horizontal plane, two dimensional), or the electronic 5 device in the pocket can attach below or above the plane of the face of the molded substrate (three dimensional, vertical plane, in the z-axis of the substrate).

Subassemblies can also be attached in the same manner as electronic devices. This could include ceramic circuitry complete 10 with active and/or passive components. It could also include ball-grid arrays or chip scale packages. Multichip Modules can also be constructed using molded substrates, chips inserted into pockets, and the attachment techniques defined in this document.

The traditional circuit board package begins with a 15 substrate which supports the circuit traces while in the Molded Electronic Package the molded substrate supports both the circuit traces and the electrical devices, and the interconnection of the components is achieved by forming the circuit traces over both the electrical devices and the substrate.

20 Connection can be directly to the electrical devices or it can be through vias (small openings or holes) in a insulating layer which covers the electrical devices. In the Molded Electronic Package connection can be directly by the trace or by a second material, such as a solder paste or a conductive adhesive that 25 is an extension of the trace.

The benefits of this construction are as follows:

- 1) Since the electronic device is securely held in the pocket by the molded substrate, the electronic device no longer relies on the adhesion of the Polymer Thick Film conductor ink to the substrate to remain secure in the circuit. Thus, this requirement of attachment or holding of the electronic device is no longer important in the selection of the Polymer Thick Film conductor used to form the circuit traces.
- 2) Interconnection options are now available that do not require the extreme high temperatures of the soldering process. We therefore have a broader choice of molding material to prepare the molded substrate making possible less expensive circuitry.
- 3) Because electronic devices, especially resistors, can be packaged in pockets in the board in the z-axis rather than mounted to the surface of the board, valuable space is now available for the attachment of other components. This is a very valuable feature when trying to design more compact circuitry.
- 4) Because a wide range of materials are available for construction of the supporting molded plastic substrate, the design engineer can take advantage of different dielectric properties such as dielectric constant, voltage breakdown resistance, and loss tangent. This only becomes possible because Molded Electronic Package packaging resolves the

problems of heat sensitivity and adhesion properties as discussed above.

5) Because electronic devices such as resistors can now be mounted under the circuit traces in pockets in the molded plastic substrate rather than on top of the traces, one can now route traces to different parts of the circuit without resorting to multi layering the circuitry to avoid crossing the traces.

6) Resistor networks can now be designed ^{to fit} below the circuit traces with a higher packaging density than possible with resistors mounted on top of the traces, because the connection joint between the trace and the electronic device is no longer also serving as the physical support for the electronic device, and therefore can be a smaller, more ^{compact} finite joint.

7) With the broader choices of polymer resins now available for the supporting substrate with the preferred embodiment of Polyether Imide but other polymer resins that may be used are Polyethylene Terephthalate, Polybutylene Terephthalate, Polyphenylene Sulfide, Polyamide, Liquid Crystal Polymers, Polyphenylene Oxide, Polycyclo Terethalate and rigid rod polyphenylene, it is now possible and practical to design, build and use circuitry that can be recycled.

8) The preparation of Molded Electronic Package circuitry can be achieved without costly, environmental risky processes, such as the use of lead solders and acids for etching, which are necessary in the current printed circuit board industry.

9) The capitalization required to set up this Molded Electronic Package process is much less than for other printed circuit board factories.

10) Since molded substrates have their physical dimensions defined in the molding process they can be easily stacked in magazines for printing and baking on automated equipment. It is not practical to process traditional circuit board substrates in this way because they must be handled in large sheets to achieve economical conversion to the final size and shape. The adaptability of the Molded Electronic Package to automated handling means its user could set up manufacturing in the country of choice instead of in cheap labor markets as is common in the printed circuit board industry today.

11) Silicon chips can be placed into pockets and attached directly to the Molded Electronic Package board without mounting them first in one of the many carrier alternatives currently used. This not only reduces cost and saves space, but allows easy rework of faulty chips by simply removing the faulty chip from the pocket, inserting a new one, and repeating the printing process which attaches the chip.

BRIEF DESCRIPTION OF THE DRAWINGS

These and other objects, features and advantages of the present invention will become apparent upon further consideration of the following detailed description of the

invention when read in conjunction with the figures, in which:

FIG. 1 is a side view of an electronic device inserted into a molded pocket and connected by a printed Polymer Thick Film conductive ink. The assembly is sealed in a solder mask.

5 FIG. 2 is a side view of an electronic device inserted into a molded pocket and connected by a printed Polymer Thick Film ink that accepts copper plating to become conductive. The electronic device also accepts plating as the means of attachment to the circuit. The assembly is sealed in a solder
10 mask.

FIG. 3 is a side view of an electronic device inserted into a molded pocket and connected by a printed Polymer Thick Film ink that is both conductive in itself and accepts copper plating to enhance its conductivity and/or solderability. The electronic
15 device does not accept the copper plating, but is connected by the adhesion of the printed Polymer Thick Film conductive ink. The assembly is sealed in solder mask.

Fig. 4 is a side view of an electronic device inserted into a molded pocket and connected to a printed Polymer Thick Film
20 ink that accepts copper plating to become conductive and solderable. The electronic device connection is made by a solder joint. The assembly is sealed in a solder mask.

FIG. 5 is a side view of an electronic device inserted into a molded pocket and sealed by a printed solder mask. Openings
25 in the solder mask (also known as vias) provide the site through

which the printed Polymer Thick Film ink is connected to the electronic device.

FIG. 6 is a side view of an electronic device inserted into a molded pocket and connected by a printed Polymer Thick Film ink that accepts copper plating to become conductive. The electronic device is sealed on its top surface by a printed solder mask, and the connection to the electronic device is made through molded vias from the reverse side of the board. In this case a conductive adhesive makes the connection between the conductive trace and the terminal sites of the electronic device.

FIG. 7 is a side view of two electronic devices inserted into two different molded pockets in the substrate. One electronic device sets slightly above and the other slightly below the horizontal plane of the substrate. Both are connected with the printing of the Polymer Thick Film conductor used to form the conductive traces of the circuit.

FIG. 8 is a side view of a subassembly inserted into a molded pocket of the substrate. This subassembly consists of several layers of circuitry and could have other electrical devices incorporated into its design. The entire subassembly is connected by the Polymer Thick Film conductive traces which are printed onto the substrate and the subassembly. The conductive material also connects the different layers of the subassembly, however, this interconnection could be intricate within the

subassembly with the Polymer Thick Film connection only made to the top surface of the subassembly.

FIG. 1 through 8 show the use of a solder mask to seal portions of the assembly. The solder mask is performing as an 5 insulating protective layer. Other printed polymer dielectrics exist for this purpose that are not solder masks. Dielectrics can offer specific electrical properties such as dielectric constant, loss tangent, and voltage breakdown properties which can be important in the design of a circuit.

10

DETAILED DESCRIPTION

The novel combination of Thick Film, Polymer Thick Film, and plastic molding technology forms the basis of the cost savings and 15 design advantages of this invention. The specific role of the molded substrate is to give form and support for the electric package. If the dielectric properties of the substrate become part of the function of the circuit, the role of the molded plastic is to optimize performance by providing the correct dielectric 20 properties. In all cases the substrate provides electrical insulation between circuit traces. The role of the ceramic Thick Film is to provide passive functions, such as resistance or capacitance, within the electrical circuit. Thick Film constructions can also provide subassemblies containing active 25 electronic devices and functions, such as transistors, diodes,

integrated circuits, and other similar devices used in the packaging of electronic circuits. The function of Polymer Thick Film in this combination is to provide the interconnecting traces of the circuit. This fills the role served by the etched copper traces of a traditional printed circuit board. The Polymer Thick Film circuit traces are deposited normally by printing. The materials that can be used for printing circuit traces include inks filled with conductive fillers, such as silver, copper, plated copper, carbon, and could include any other filler that produces a suitable electrical conductive current path. The Polymer Thick Film conductor can also be a non conductive material which, when printed, provides a sensitized trace which accepts metal plating, and in this way produces an electrically conductive path. The metal deposited in the plating process will provide the conductivity while the printing material only defines the image to selectively accept metal plating.

Polymer Thick Film materials can also provide other functions within the circuitry, such as resistance, capacitance, and dielectric separation between layers of a multilayer construction. These functions can be part of the total construction, but are not novel to this invention. It is the interconnection of the electronic devices that are held within the molded frame that is an improvement over existing technology.

Throughout this description electronic device is defined as a passive component which serves a function within the circuit such

as a resistor or capacitor, or an active component such as a transistor or a diode or a silicon chip. An electronic device can also be a plastic ball grid array or a chip scale package, or a subassembly of circuitry and components. An electronic device can

5 also be an electromechanical device such as a connector pin or an off/on switch, or a bioelectrical component.

Throughout this description a molded substrate is defined as a support for an electronic circuit molded from any available plastic resin suitable for the purpose such as Polyether Imide

10 which is preferred for its combination of low cost, ability to withstand high temperature exposures as experienced in a commercial soldering process, ability to mold flat, remain flat throughout subsequent processing, and its formation of strong adhesive bonding with most Polymer Thick Film inks. Other plastics that can be used

15 to construct molded substrates include, but are not limited to Epoxies, Phenolics, thermoset Polyesters, Polyethylene Terephthalate, Polybutylene Terephthalate, Polyphenylene Sulfide, Polyamide polymers and copolymers, Liquid Crystal Polymers, Polyphenylene Oxide, Polycyclo Terethalate, Syndiotactic Polystyrene, and rigid

20 rod Polyphenylenes. In the examples given in this description a specific size is given for the pocket and the electronic device inserted into the pocket. This is a practical and convenient size, both for an example and for actual assembly, however the specific size is given for example only, and an infinite number of sizes

25 could be used.

Throughout this description a Polymer Thick Film conductor ink is defined as any ink, screen printed, pad printed, or printed with any other commercial process which deposits material that upon processing will conduct electricity with a resistivity low enough 5 for the print to serve as a conductive trace in an electronic circuit. This is normally less than one tenth of an ohm per square in sheet resistance as printed. Examples of Polymer Thick Film conductor inks are Asahi LS 504J Silver, Asahi LS 506J silver, Asahi Copper CU-051, and Grace 4001 Silver.

10 Throughout this description a fusible Polymer Thick Film conductive ink is defined as an ink which contains metal fillers which upon processing melt and solidify in a manner similar to solder reflowing, and which upon processing form an adhesive bond to the supporting substrate. Such inks usually have low 15 resistivity and are capable of accepting solder to form a solder joint between a conductive trace and a electronic device. An example of a fusible conductor inks is SVT EU 1328 and Kester Ormet 1200, and Kester Ormet 2005.

Throughout this description a conductive adhesive is defined 20 as a blend of polymers and conductive fillers such as metals which when applied joins a circuit trace and a electronic device and upon processing forms a conductive joint.

Fig.1 shows the molded substrate 1 holding an electronic device 2. The traces are connected in the circuit by a printed 25 Polymer Thick Film material 3 such as Asahi LS 504 J Silver ink

that produces both conductivity for the circuit traces and connection to the component. The substrate is shown as planar (flat), but may also be non-planar (not flat - three dimensional). A solder mask layer 4 seals the package. The advantage to this 5 process is that the silver ink is easy to use and has fewer processing steps. The disadvantage is that silver inks have more resistance than copper foil, and they normally do not accept solder as may be required in some other assembly process. The point of attachment 5 between the conductive trace and the electronic device 10 is where the conductive ink falls directly onto the electronic device. The ink forms an adhesive bond to the component making the electrical connection. The ink can also be a fusible Polymer Thick Film conductive ink such as SVT EU 1328 which accepts solder attachment and therefore has an advantage over conventional silver 15 inks.

FIG. 2 shows a variation of this concept where the molded substrate 1 holds an electronic device 2. The traces may be connected in the circuit by a printed Polymer Thick Film material 6 that has been plated with copper 7 to produce both conductivity 20 and electrical connection to the electronic component. A solder mask 4 layer has sealed the package. Notice that no solder is needed to connect the traces to the electronic device. The plating process provides both a conductive path and connection, or the point of attachment 5, to the electronic device. The Polymer Thick 25 Film conductive trace can be a non-conductive sensitizing ink such

Technologies EU 1328, or any material by any manufacturer that performs in a manner similar to those mentioned. The advantage of this variation is a broader choice of electronic devices that can be connected in this manner, and the ability to design a product 5 to meet specific performance requirements such as flexibility of the substrate base, heat stability, or the reduction in lead content. The circuit is protected by a solder mask or dielectric layer 4. The point of attachment 5 is then a combination of the bonding between the copper plating 7 and the solder (or conductive 10 adhesive) 8 which bonds to both the copper plating 7 and the component 2.

FIG. 5 shows another variation of this concept where a Polymer dielectric layer such as a solder mask 4 covers the molded substrate 1 so that the surface chemistry of the surface to which 15 the polymer conductive trace 3 must bond is enhanced. The layer can either cover only the molded surface or it may cover both the molded plastic and a portion of the electronic device. If the electronic device 2 is covered, attachment to the electronic device is through vias in the dielectric layer 4 of the circuit. A 20 fusible Polymer Thick Film conductive ink such as SVT EU1328 is used and a surface mount electronic device 9 is placed onto the ink traces while the ink is still wet. The assembly is processed in a hot vapor reflow oven at 215° C for two minutes which attaches a surface mount electronic device and forms the point of attachment 25 5 for the inserted electronic device.

devices making an electrical connection. Even though devices 2 and 9 are not flat with the substrate 1, attachment is still possible and situations may arise where this condition may even be preferable.

5 Fig. 8 shows the molded substrate 1 holding a multilayer subassembly 10 in the pocket of the substrate 1. The traces are printed to form a circuit using a Polymer Thick Film material 3 such as Asahi LS 504J silver ink or SVT EU 1328 fusible conductive ink that produces both conductivity for the circuit traces and
10 10 connection 5 to the multilayer subassembly 10. The point of attachment 5 between the conductive trace and the subassembly is where the conductive ink falls 3 directly onto the multilayer subassembly. All layers of the multilayer can be attached at this point, or they can be independently connected within its own
15 15 structure. The ability to place more than one electrical device or multilayer subassemblies which can have layers of circuitry on each surface used to construct the multilayer expands greatly the functionality of the package.

Another variation of this invention is that of an active
20 20 electronic device, such as a silicon chip, can be connected in the circuit in any of the processes shown in FIG. 1 - 8.

Another variation of this invention is that a subassembly, such as ceramic circuit to which other components are, or can be, attached.

25 Another variation of this invention is when electronic

devices made on separate plastic moldings are inserted into the Molded Electronic Package in place of the ceramic Thick Film components or sub assemblies.

Another variation of this invention is when electronic
5 devices made on printed circuit board materials such as FR4, FR2, CEM1, CEM3, and polyimide laminate are inserted into the Molded Electronic Package in place of the ceramic Thick Film electronic devices or sub assemblies

Example 1. A substrate is molded of a preferred material
10 commonly called Polyether Imide, but may be molded from such materials as but not limited to Polyethylene Terephthalate, Polybutylene Terephthalate, Polyphenylene Sulfide, Polyamide, Liquid Crystal Polymers, Polyphenylene Oxide, Polycyclo Terethalate, thermoset Epoxies, thermoset polyester, thermoset
15 Phenolic, syndiotactic polystyrene or a rigid rod polyphenylenes. The molded substrate contains a pocket 0.5 cm by 1.25 cm and 0.25 cm deep. A ceramic substrate of the same or slightly smaller dimensions on which is printed a resistor array is placed in this pocket. Circuit traces are printed on the molded
20 substrate with a Polymer Thick Film conductive ink such as Asahi LS 504 J and cured at 140° C in a box oven for 30 minutes or on a conveyorized infrared belt furnace at a setting to give the same degree of cure. The circuit traces terminate directly on the

terminal sites of the electronic device, and in this way attachment is achieved. This attachment is simultaneous with the formation of the circuit on the substrate.

Example 2. A substrate is molded of a suitable material 5 such as described in Example 1 and fitted with an electronic device inserted into a molded pocket as described in Example 1. Circuit traces are printed on the molded substrate with a Polymer Thick Film conductive ink such as Asahi ACP - 007-2P copper paste and cured at 150° C for 30 minutes in a box oven or 10 on a conveyorized infra red belt furnace at a setting to produce the same degree of cure. The circuit traces terminate directly on the terminal sites of the electronic device. The assembly is placed in an electroless copper bath such as Enthone CU-705. As 15 copper plated on the electronic device and the Polymer Thick Film traces the circuit become electrically conductive, and at the same time attachment of the electronic device is achieved.

Example 3. A substrate is molded of a material such as described in Example 1 and fitted with an electronic device inserted into a molded pocket as described in Example 1. 20 Circuit traces are printed on the substrate with a Polymer Thick Film conductive ink such as Asahi ACP - 051 copper paste and cured at 150 degrees C for 30 minutes in a box oven, or on a conveyorized infra red belt furnace at a setting to produce the

same degree of cure. The circuit traces terminate directly on the terminal sites of the electronic device, and in this way attachment of the electronic device is achieved. This attachment is simultaneous with the formation of the circuit on 5 the substrate. The circuit is naturally solderable and other electronic devices can be attached by soldering. The circuit can also be copper plated as in Example 2 to enhance conductivity, solderability, and or the quality of the attachment to the electronic device in the pocket.

10 Example 4. A substrate is molded of a material such as described in Example 1 and fitted with an electronic device in the molded pocket as in Example 1. Circuit traces are printed on the molded substrate with a Polymer Thick Film conductive ink such as Asahi ACP - 007-2P copper paste and cured at 150 degrees 15 C for 30 minutes in a box oven, or on a conveyorized infra red belt furnace at a setting to produce the same degree of cure. The circuit traces terminate next to but not directly on the terminal sites of the electronic device. The assembly is placed in an electroless copper bath such as Enthone CU-705. As copper. 20 plates onto the Polymer Thick Film traces the circuit become electrically conductive. Attachment of the electronic device is achieved by applying and reflowing a solder paste such as Multicore WS 12AAS88.

Example 5. An alternative to Example 4 is to make the

Example 7. A substrate is molded of a material such as described in Example 1, and fitted with an electronic device inserted into a molded pocket as described in Example 1. The entire surface of the assembly is sealed with a dielectric print

5 using Asahi CR-20G dielectric ink. Circuit traces are printed on the reverse, or back side of the board using Asahi ACP-007-2P copper ink which is cured at 150° C for 30 minutes in a box oven or on a conveyorized infra red belt furnace at a setting to produce the same degree of cure. The assembly is placed in an

10 electroless copper bath such as Enthone CU-705 for the proper amount of time to achieve an electroless deposition of copper on the printed traces. This usually requires about 30 to 45 minutes. Vias have been molded in the substrate to give access to the termination site of the component from the reverse, or

15 back side of the substrate. A conductive adhesive such as Multicore's M-4030 Ag/TP is deposited to achieve an electrical connection between the conductive traces and the termination sites of the electronic device which are exposed by the vias in the molded substrate.

20 Example 8. In examples 1 - 7 the components have termination sites to which attachments are made, but they do not have leads (metal wires or flat metal extensions from the termination sites). Any of the electronic devices in examples 1

- 7 that can be acquired as leaded components are assembled in this example by mounting them in molded pockets that support the device and its leads is such a position that allows interconnection to be made to the leads of the device using the

5 Polymer Thick Film materials and processing described in examples 1 - 7.

Example 9. A substrate is molded of a material such as described in Example 1 and fitted with a chip. Circuit traces are printed with Polymer Thick Film that connect to the chip as

10 in Examples 1 through 7 to form a smart card.

While the present invention has been described with respect to preferred embodiments, numerous modifications, changes, and improvements will occur to those skilled in the art without departing from the spirit and scope of the invention.

15

20

CLAIMS

What I claim is:

1. An electronic package structure comprising:
a molded substrate having first and second opposing
5 surfaces and an electronic device disposed on one of the said
surfaces:
said molded substrate having a molded pocket on one of said
opposing surfaces into which said electronic device is supported
in said pocket; wherein said electronic device is connected via
10 Polymer Thick Film printed on the surface of said molded
substrate and exposed surface of the electronic device contained
in the molded pocket.
2. The structure of claim 1, wherein said Polymer Thick
Film printed on the surface of the molded substrate and exposed
15 surface of the electronic device contained in the molded pocket
lie substantially in a plane.
3. The structure of claim 1, wherein the Polymer Thick
Film printed on the surface of said molded substrate and exposed
surface of the electronic device contained in the molded pocket
20 are in a non-planer configuration to each other.
4. The structure of claim 3, wherein said device in the
pocket is below the primary surface of one of the said molded
substrate.

5. The structure of claim 3, wherein said device in said pocket protrudes above a primary surface of a first molded substrate.

6. The structure of claim 1, wherein the contact surface 5 of said device in the molded substrate pocket are accessed from the surface opposite said pocket through vias.

7. The structure of claim 1, wherein contact surfaces of said device are sealed with a printed layer having a via whereby a device is attached to the trace.

10 8. The structure of claim 1, wherein said electronic device is a resistor.

9. The structure of claim 1, wherein said electronic device is a capacitor.

10. The structure of claim 1, wherein said electronic 15 device is an LED.

11. The structure of claim 1, wherein said electronic device is an electromechanical device.

12. The structure of claim 1, wherein said electronic device is an connector pin.

20 13. The structure of claim 1, wherein said electronic device is an bioelectrical functional component.

14. The structure of claim 1, wherein said electronic device is a ceramic Thick Film.

15. The structure of claim 1, wherein said electronic device is a Polymer Thick Film.
16. The structure of claim 1, wherein said electronic device is ball-grid array.
- 5 17. The structure of claim 1, wherein said electronic device is a chip scale package.
18. The structure of claim 1, wherein said electronic device is a Multichip Modules.
19. The structure of claim 1, wherein said Polymer Thick Film printed on the surface of said molded substrate and electronic device are connected by a second Polymer Thick Film being deposited on the first Polymer Thick Film as a second material which is an extension of the trace.
20. The structure of claim 1, wherein the connection is made by using an electronic device and Polymer Thick Film ink that accepts copper plating to become conductive.
21. The structure of claim 1, wherein the electronic device does not accept copper plating but is connected by the adhesion of the printed Polymer Thick Film conductive ink and whereby the Polymer Thick Film is both conductive in itself and accepts copper plating to enhance its conductivity or solderability.

22. The structure of claim 1, wherein said electronic device connected to a Polymer Thick Film ink that accepts copper plating to become conductive and solderable, and wherein the electronic connection to the electronic device is made by a 5 solder joint.

23. The structure of claim 1, wherein said electronic device and substrate is sealed with a solder mask, openings in the solder mask or vias provide the site through which the printed Polymer Thick Film ink is connected to the electronic 10 device.

24. The structure of claim 1, wherein the electronic device inserted in a molded pocket and connected by a printed Polymer Thick Film ink that accepts copper plating to become conductive, wherein the electronic device is sealed on its top 15 surface by a printed solder mask, whereas the electronic device is connected through molded vias from the reverse side of the substrate, and whereas a conductive adhesive makes the connection between the conductive trace and the terminal sites of the electronic device.

20 25. The structure of claim 1, wherein two electronic devices are placed in a plurality of pockets in the molded substrate and interconnected by printing of the Polymer Thick Film conductor used to form the conductive traces of the circuit.

26. The structure of claim 1, wherein said electronic device is an entire subassembly which is interconnected with a Polymer Thick Film printing of a trace at the top of the surface of the subassembly.

5 27. The structure of claim 26, wherein said subassembly is interconnected with the Polymer Thick Film connecting the different layers of the subassembly.

28. The structure of claim 1, wherein the molded substrate is molded from resin of Polyether Imide.

10 29. The structure of claim 1, wherein the molded substrate is molded from resin of Polyethylene Terephthalate.

30. The structure of claim 1, wherein the molded substrate is molded from resin of Polybutylene Terephthalate.

31. The structure of claim 1, wherein the molded substrate
15 is molded from resin of Polyphenylene Sulfide.

32. The structure of claim 1, wherein the molded substrate is molded from resin of Polyamide.

33. The structure of claim 1, wherein the molded substrate is molded from resin of Liquid Crystal Polymers.

20 34. The structure of claim 1, wherein the molded substrate is molded from resin of Polyphenylene Oxide.

35. The structure of claim 1, wherein the molded substrate is molded from resin of Polycyclo Terethatlate.

36. The structure of claim 1, wherein the molded substrate is molded from resin of rigid rod Polyphenylene.

37. The structure of claim 1, wherein the molded substrate is molded from resin of epoxies.

5 38. The structure of claim 1, wherein the molded substrate is molded from resin of phenolics.

39. The structure of claim 1, wherein the molded substrate is molded from resin of thermoset Polyesters.

40. The structure of claim 1, wherein the molded substrate 10 is molded from resin of syndiotactic Polystyrene.

41. A process for assembling electronic circuitry comprising the steps of:

- a) Molding a substrate of a plastic material;
- b) In the molding of said substrate forming a pocket in 15 said substrate to hold an electronic device in said pocket;
- c) Depositing an electronic device in one of said pockets;
- d) Printing circuit traces on said molded substrate with a Polymer Thick Film conductive ink;
- e) Curing said ink by heating;
- f) Wherein said traces terminate directly on terminal 20 sites of said electronic device; and
- g) Whereby attachment is achieved simultaneous with the formation of a circuit on said substrate.

42. The structure of claim 41, wherein said Polymer Thick Film printed on the surface of the molded substrate and exposed surface of the electronic device contained in the molded pocket lie substantially in a plain.

5 43. The structure of claim 41, wherein the Polymer Thick Film printed on the surface of said molded substrate and exposed surface of the electronic device contained in the molded pocket are in a non-planer configuration to each other.

10 44. The structure of claim 43, wherein said device in the pocket is below the primary surface of one of the said molded substrate.

45. The structure of claim 43, wherein said device in said pocket protrudes above a primary surface of a first molded substrate.

15 46. The structure of claim 41, wherein the contact surface of said device in the molded substrate pocket are accessed from the surface opposite said pocket through vias.

20 47. The structure of claim 41, wherein contact surfaces of said device are sealed with a printed layer having a via whereby a device is attached to the trace.

48. The structure of claim 41, wherein said electronic device is a resistor.

49. The structure of claim 41, wherein said electronic device is a capacitor.

50. The structure of claim 41, wherein said electronic device is an LED.

51. The structure of claim 41, wherein said electronic device is an electromechanical device.

5 52. The structure of claim 41, wherein said electronic device is an connector pin.

53. The structure of claim 41, wherein said electronic device is an bioelectrical functional component.

10 54. The structure of claim 41, wherein said electronic device is a ceramic Thick Film.

55. The structure of claim 41, wherein said electronic device is a Polymer Thick Film.

56. The structure of claim 41, wherein said electronic device is ball-grid array.

15 57. The structure of claim 41, wherein said electronic device is a chip scale package.

58. The structure of claim 41, wherein said electronic device is a Multichip Modules.

20 59. The structure of claim 41, wherein said Polymer Thick Film printed on the surface of said molded substrate and electronic device are connected by a second Polymer Thick Film being deposited on the first Polymer Thick Film as a second material which is an extension of the trace.

60. The structure of claim 41, wherein the connection is made by using an electronic device and Polymer Thick Film ink that accepts copper plating to become conductive.

61. The structure of claim 41, wherein the electronic device does not accept copper plating but is connected by the adhesion of the printed Polymer Thick Film conductive ink and whereby the Polymer Thick Film is both conductive in itself and accepts copper plating to enhance its conductivity or solderability.

62. The structure of claim 41, wherein said electronic device connected to a Polymer Thick Film ink that accepts copper plating to become conductive and solderable, and wherein the electronic connection to the electronic device is made by a solder joint.

63. The structure of claim 41, wherein said electronic device and substrate is sealed with a solder mask, openings in the solder mask or vias provide the site through which the printed Polymer Thick Film ink is connected to the electronic device.

64. The structure of claim 41, wherein the electronic device inserted in a molded pocket and connected by a printed Polymer Thick Film ink that accepts copper plating to become conductive, wherein the electronic device is sealed on its top 5 surface by a printed solder mask, whereas the electronic device is connected through molded vias from the reverse side of the substrate, and whereas a conductive adhesive makes the connection between the conductive trace and the terminal sites of the electronic device.

10 65. The structure of claim 41, wherein two electronic devices are placed in a plurality of pockets in the molded substrate and interconnected by printing of the Polymer Thick Film conductor used to form the conductive traces of the circuit.

15 66. The structure of claim 41, wherein said electronic device is an entire subassembly which is interconnected with a Polymer Thick Film printing of a trace at the top of the surface of the subassembly.

20 67. The structure of claim 66, wherein said subassembly is interconnected with the Polymer Thick Film connecting the different layers of the subassembly.

68. The structure of claim 41, wherein the molded substrate is molded from resin of Polyether Imide.

69. The structure of claim 41, wherein the molded substrate is molded from resin of Polyethylene Terephthalate.

70. The structure of claim 41, wherein the molded substrate is molded from resin of Polybutylene Terephthalate.

5 71. The structure of claim 41, wherein the molded substrate is molded from resin of Polyphenylene Sulfide.

72. The structure of claim 41, wherein the molded substrate is molded from resin of Polyamide.

10 73. The structure of claim 41, wherein the molded substrate is molded from resin of Liquid Crystal Polymers.

74. The structure of claim 41, wherein the molded substrate is molded from resin of Polyphenylene Oxide.

75. The structure of claim 41, wherein the molded substrate is molded from resin of Polycyclo Terethatlate.

15 76. The structure of claim 41, wherein the molded substrate is molded from resin of rigid rod Polyphenylene.

77. The structure of claim 41, wherein the molded substrate is molded from resin of epoxies.

78. The structure of claim 41, wherein the molded substrate is molded from resin of phenolics.

20 79. The structure of claim 41, wherein the molded substrate is molded from resin of thermoset Polyesters.

80. The structure of claim 41, wherein the molded substrate is molded from resin of Syndiotactic Polystyrene.

81. The structure of claim 1, wherein the said electronic device is a leaded component.

5 82. The structure of claim 41, wherein the said electronic device is a leaded component.

83. An electronic smart card comprising a chip assembled according to claim 1.

10 84. An electronic smart card comprising a chip assembled according to claim 41.

85. The structure of claim 1, wherein the said electronic device is surface mounted onto the printed traces and attached by curing the Polymer Thick Film.

15 86. The structure of claim 41, wherein the said electronic device is surface mounted onto the printed traces and attached by curing the Polymer Thick Film.

ABSTRACT

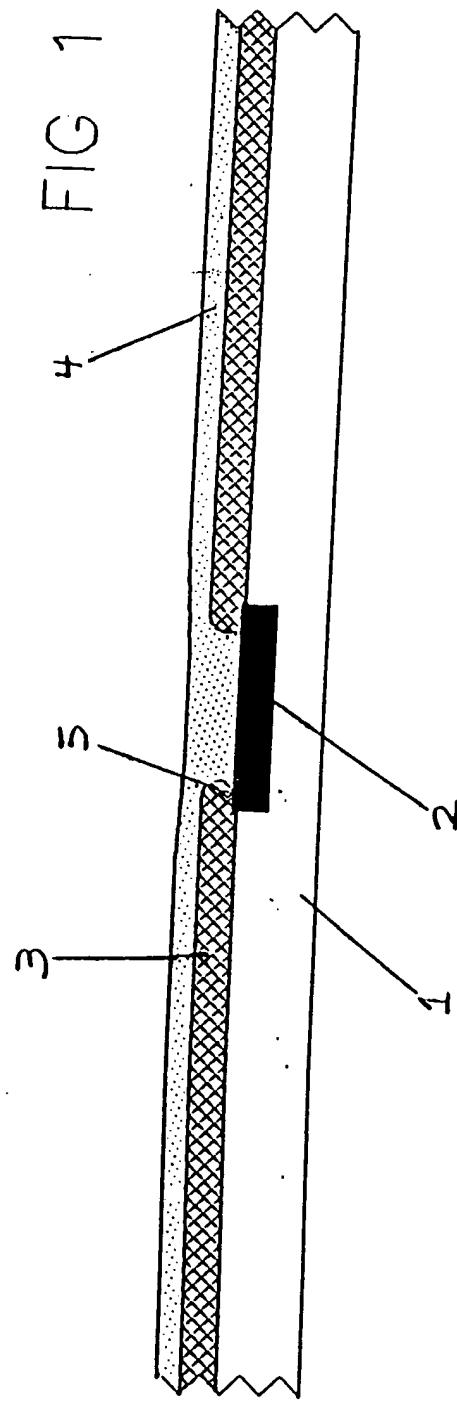
An improved way of preparing packaged electronic circuitry using molded plastics, ceramic Thick Film technology, and Polymer Thick 5 Film technology. In this invention at least one of the electronic devices in the package is supported in a plastic molded substrate, and the circuit traces area added to the surface of the electronic device.

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FIG 1



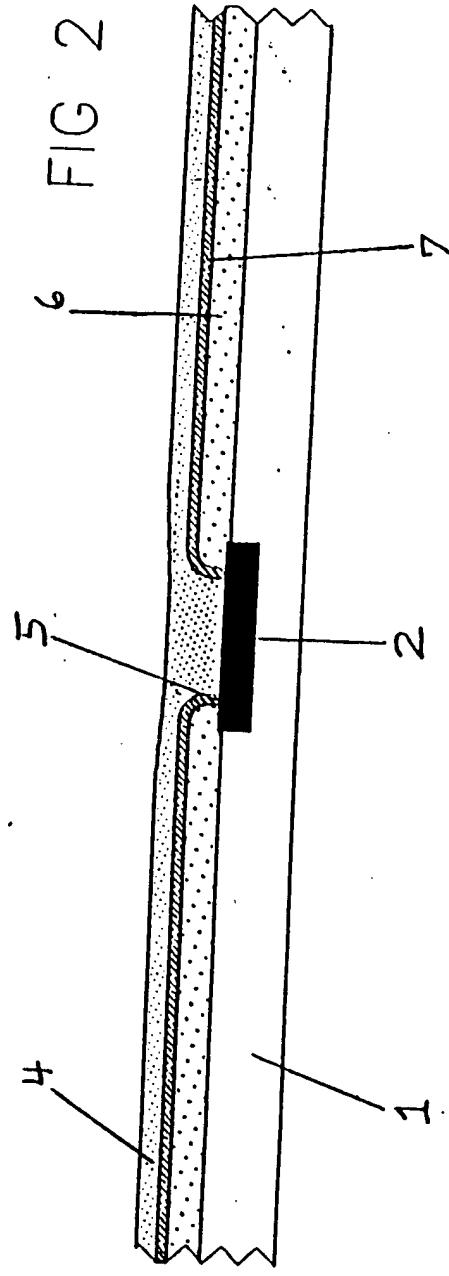


FIG 3

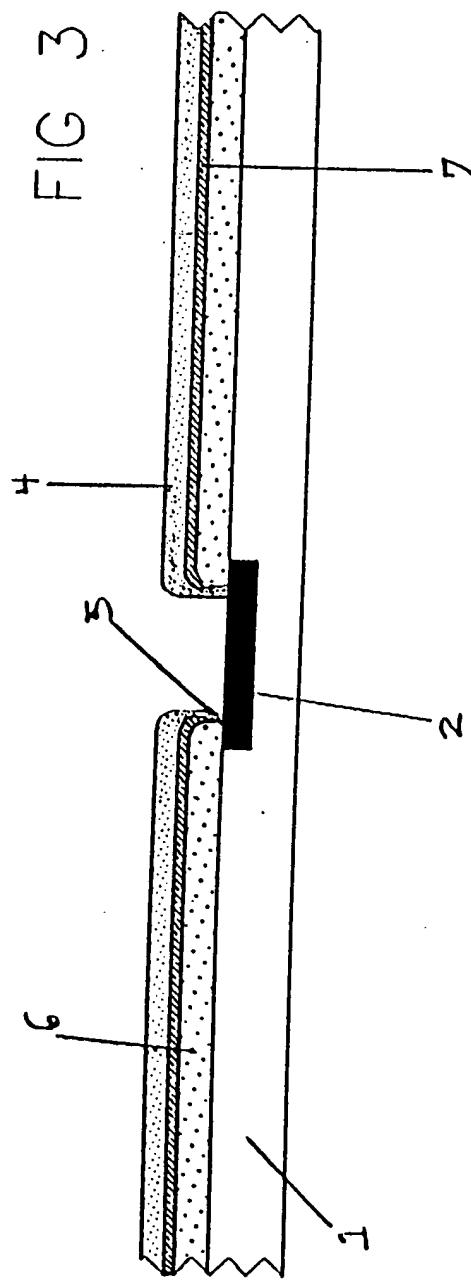


FIG 4

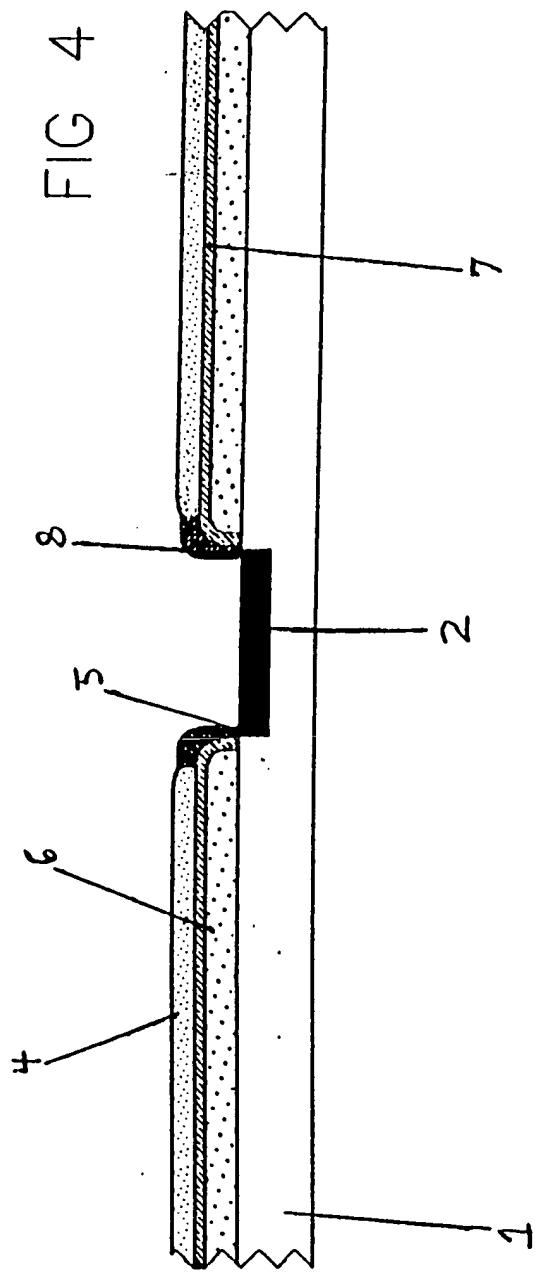


FIG 5

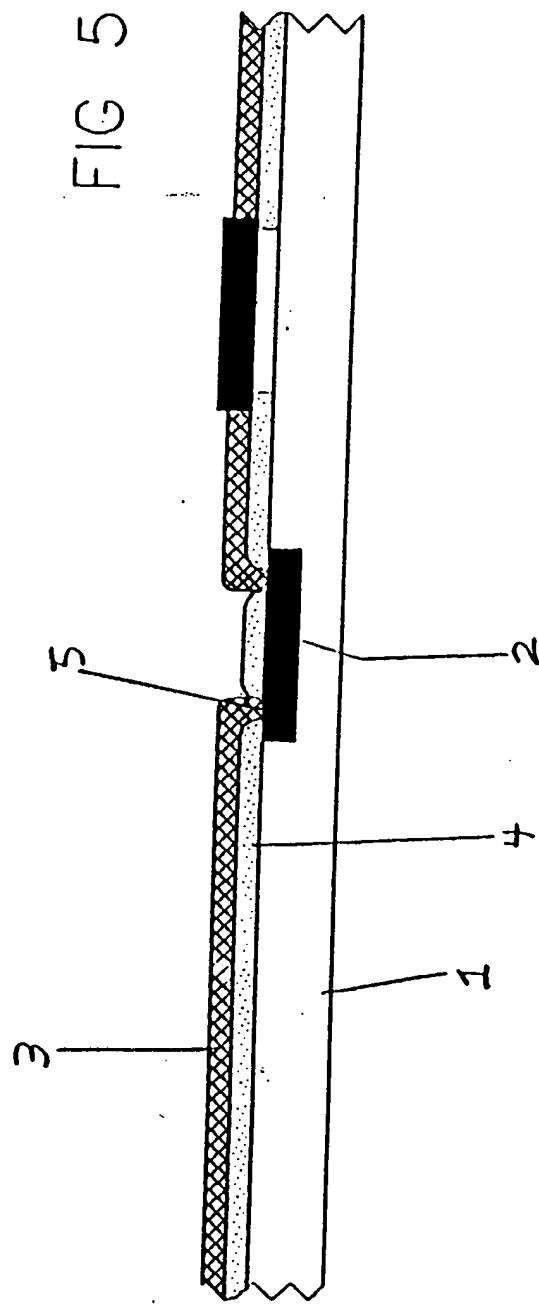
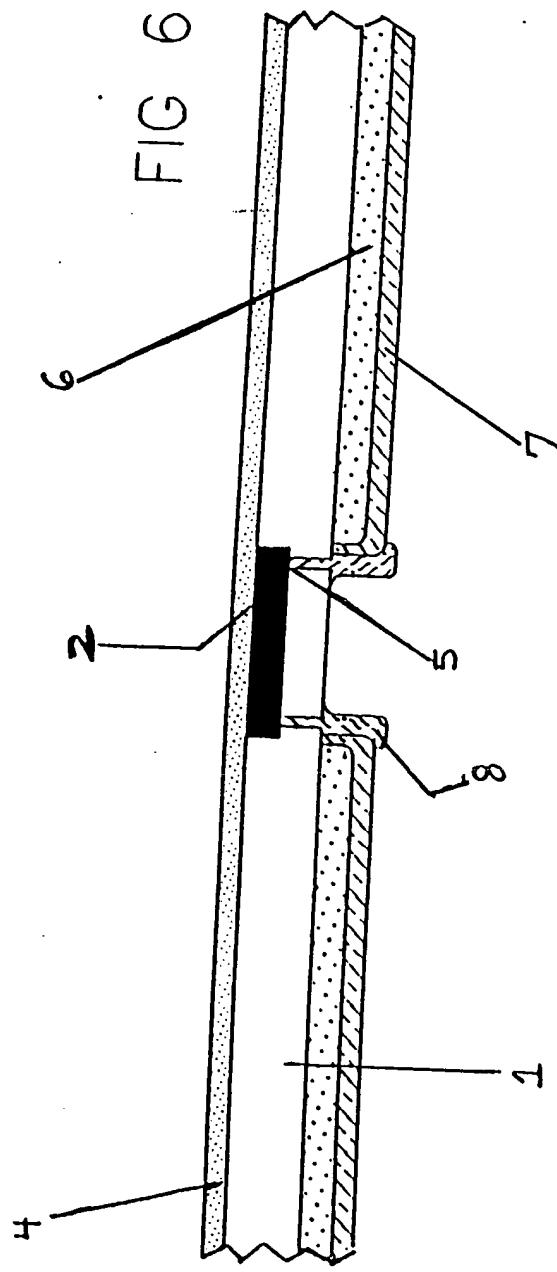


FIG 6



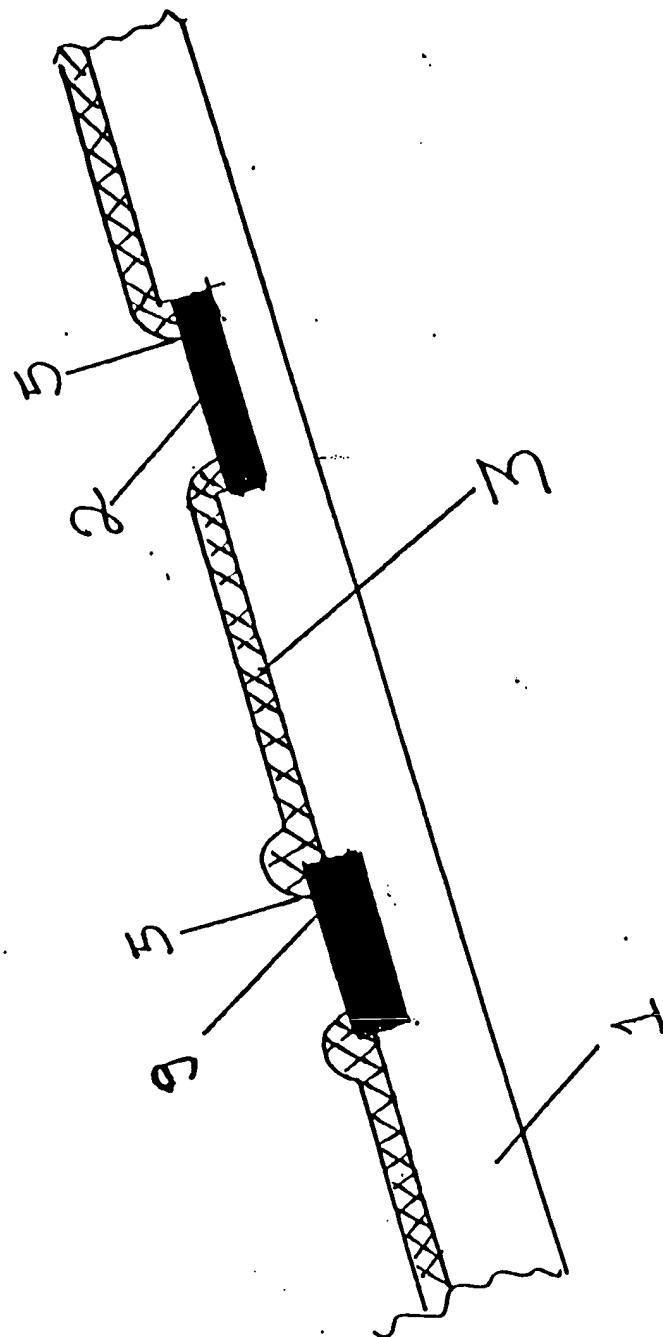


FIG 7

FIG. 8

